

# **HVD145**

# Silicon Epitaxial Planar Pin Diode for Antenna Switching

REJ03G0430-0200

(Previous: ADE-208-1507A)

Rev.2.00

Dec 07, 2004

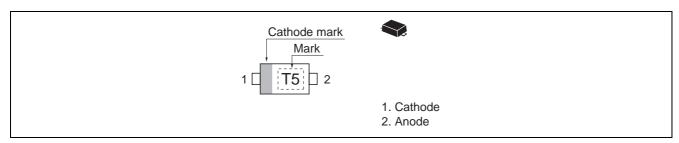
### **Features**

- An optimal solution for antenna switching in mobile phones.
- Low capacitance. (C = 0.45 pF max)
- Low forward resistance. (rf =  $1.8 \Omega \text{ max}$ )
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

## **Ordering Information**

Type No.	Laser Mark	Package Code
HVD145	T5	SFP

### **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Reverse voltage	V <sub>R</sub>	60	V
Forward current	I <sub>F</sub>	50	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

## **Electrical Characteristics**

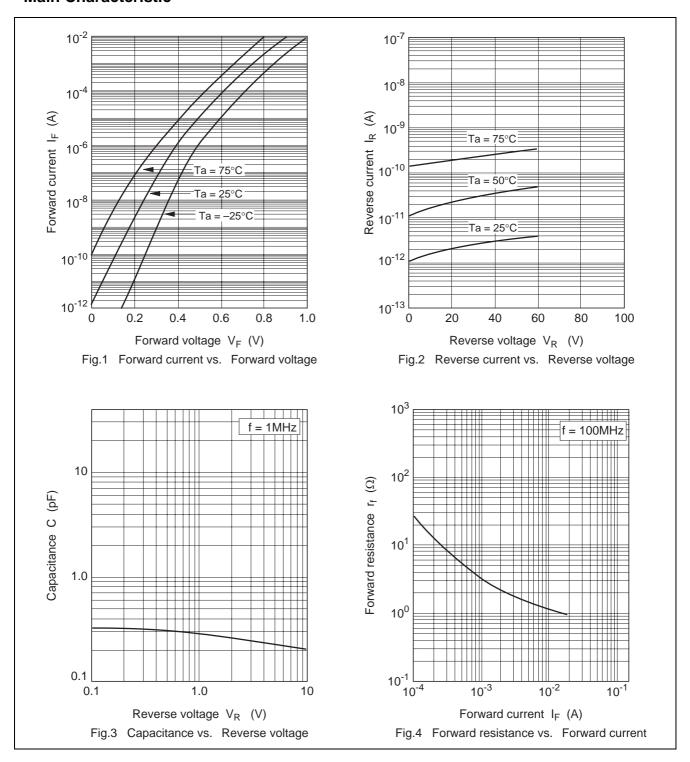
 $(Ta = 25^{\circ}C)$ 

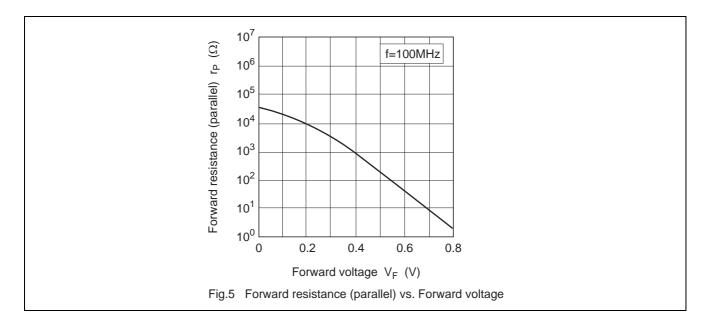
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R</sub>	_	_	100	nA	V <sub>R</sub> = 60 V
Forward voltage	V <sub>F</sub>	_	_	0.9	V	$I_F = 2 \text{ mA}$
Capacitance	С	_	_	0.45	pF	V <sub>R</sub> = 1 V, f = 1 MHz
Forward resistance	r <sub>f</sub>	_	_	1.8	Ω	I <sub>F</sub> = 10 mA, f = 100 MHz
ESD-Capability *1	_	100	_	_	V	$C = 200 \text{ pF}, R = 0 \Omega$ , Both forward
						and reverse direction 1 pulse.

Notes: 1. Failure criterion ;  $I_R > 100$  nA at  $V_R = 60$  V

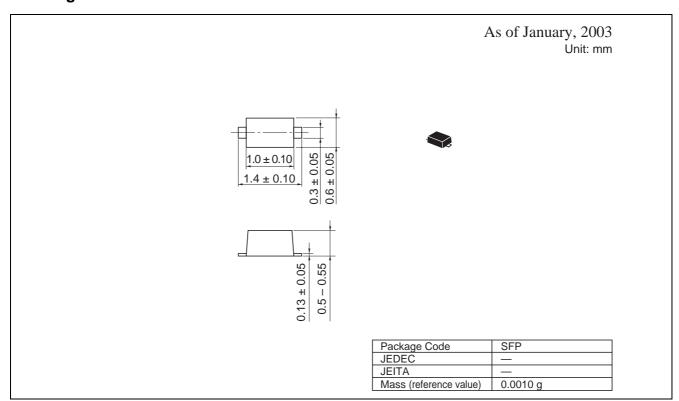
2. Please do not use the soldering iron due to avoid high stress to the SFP package.

### **Main Characteristic**





## **Package Dimensions**



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